

**General Description**

The MY15N10C uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

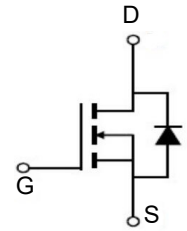
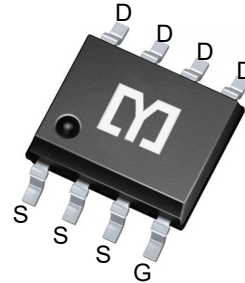


: YUhi fYg

|                            |       |     |
|----------------------------|-------|-----|
| $X_{FUU}$                  | 100   | X   |
| $K$                        | 37    | C   |
| $T_{FUQP} + cVXI U? 32X+$  | > ; 4 | o á |
| $T_{FUQP} + cVXI U? 4.5X+$ | > ; 9 | o á |

**Application**

- Battery protection
- Š[ œÁ, œ&@
- Wj q c"i~ ] œ^Á[ , ^!Á~ ] ] |



**DUW U[ Y A Uf \_]b[ UbX CfXYf]b[ -bZfa U]cb**

| DfcXi Wi-8 | DUW  | A Uf _]b[ | E lmfD7 GŁ |
|------------|------|-----------|------------|
| MY15N10C   | ÙUÙÈ | 1510C     | HÈÈÈ       |

5 Vgc`i hY'AU ]a i a 'FU]b[ g'fH, 1&) °C unless otherwise noted)

| Symbol                | Parameter  | Rating     | Units |
|-----------------------|--|------------|-------|
| $V_{DS}$              | Drain-Source Voltage                             | 100        | V     |
| $V_{GS}$              | Gate-Source Voltage                              | ±20        | V     |
| $I_D@T_A=25^{\circ}C$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 15         | A     |
| $I_D@T_A=70^{\circ}C$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 7          | A     |
| $I_{DM}$              | Pulsed Drain Current <sup>2</sup>                | 30         | A     |
| EAS                   | Single Pulse Avalanche Energy <sup>3</sup>       | 6.1        | mJ    |
| $I_{AS}$              | Avalanche Current                                | 11         | A     |
| $P_D@T_A=25^{\circ}C$ | Total Power Dissipation <sup>3</sup>             | 1.5        | W     |
| $T_{STG}$             | Storage Temperature Range                        | -55 to 150 | °C    |
| $T_J$                 | Operating Junction Temperature Range             | -55 to 150 | °C    |
| $R_{\theta JA}$       | Thermal Resistance Junction-ambient <sup>1</sup> | 85         | °C/W  |
| $R_{\theta JC}$       | Thermal Resistance Junction-Case <sup>1</sup>    | 36         | °C/W  |

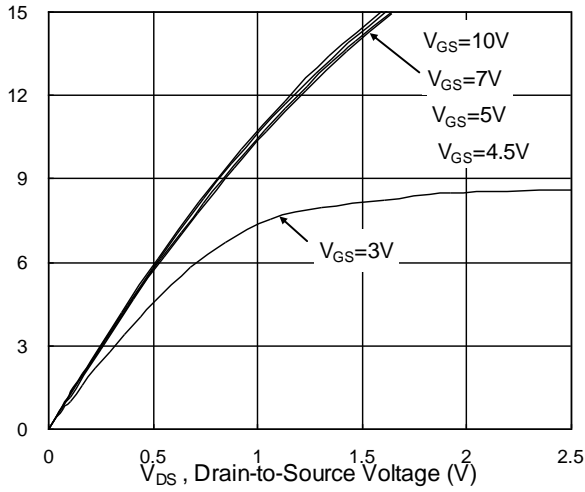
**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

| Symbol                              | Parameter                                      | Conditions  | Min. | Typ.  | Max. | Unit  |
|-------------------------------------|--|---|------|-------|------|-------|
| BV <sub>DSS</sub>                   | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA  | 100  | ---   | ---  | V     |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25 °C, I <sub>D</sub> =1mA   | ---  | 0.098 | ---  | V/°C  |
| R <sub>DS(ON)</sub>                 | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> =2A  | ---  | 90    | 112  | mΩ    |
|                                     |  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =1A   | ---  | 95    | 120  | mΩ    |
| V <sub>GS(th)</sub>                 | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA                            | 1.0  | 1.5   | 2.5  | V     |
| ΔV <sub>GS(th)</sub>                | V <sub>GS(th)</sub> Temperature Coefficient    |   | ---  | -4.57 | ---  | mV/°C |
| I <sub>DSS</sub>                    | Drain-Source Leakage Current                   | V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =25 °C                    | ---  | ---   | 10   | μA    |
|                                     |  | V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>J</sub> =55 °C                    | ---  | ---   | 100  |       |
| I <sub>GSS</sub>                    | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V  | ---  | ---   | ±100 | nA    |
| g <sub>fs</sub>                     | Forward Transconductance                       | V <sub>DS</sub> =5V, I <sub>D</sub> =2A   | ---  | 12    | ---  | S     |
| R <sub>g</sub>                      | Gate Resistance                                | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz                                    | ---  | 2     | 4    |       |
| Q <sub>g</sub>                      | Total Gate Charge (10V)                        | V <sub>DS</sub> =60V, V <sub>GS</sub> =10V, I <sub>D</sub> =2A                      | ---  | 19.5  | ---  | nC    |
| Q <sub>gs</sub>                     | Gate-Source Charge                             |   | ---  | 3.2   | ---  |       |
| Q <sub>gd</sub>                     | Gate-Drain Charge                              |   | ---  | 3.6   | ---  |       |
| T <sub>d(on)</sub>                  | Turn-On Delay Time                             | V <sub>DD</sub> =50V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3, I <sub>D</sub> =1A | ---  | 16.2  | ---  | ns    |
| T <sub>r</sub>                      | Rise Time                                      |   | ---  | 3     | ---  |       |
| T <sub>d(off)</sub>                 | Turn-Off Delay Time                            |   | ---  | 44    | ---  |       |
| T <sub>f</sub>                      | Fall Time                                      |   | ---  | 2.6   | ---  |       |
| C <sub>iss</sub>                    | Input Capacitance                              | V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz                                   | ---  | 1535  | ---  | pF    |
| C <sub>oss</sub>                    | Output Capacitance                             |   | ---  | 60    | ---  |       |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                   |   | ---  | 37.4  | ---  |       |
| I <sub>S</sub>                      | Continuous Source Current <sup>1,5</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current                                   | ---  | ---   | 4    | A     |
| I <sub>SM</sub>                     | Pulsed Source Current <sup>2,5</sup>           |   | ---  | ---   | 8    | A     |
| V <sub>SD</sub>                     | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25 °C                      | ---  | ---   | 1.2  | V     |

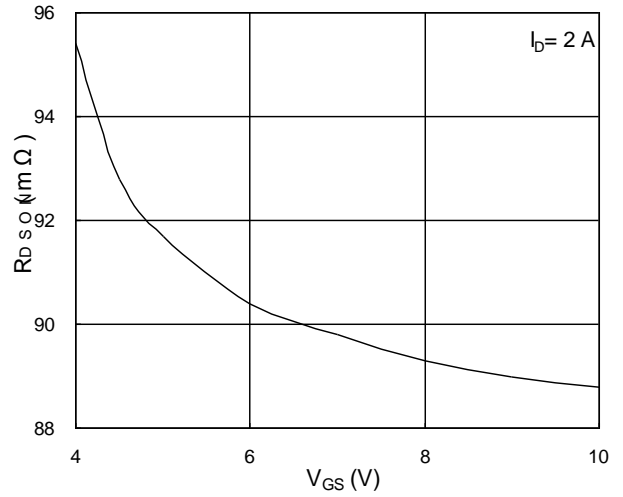
**Note :**

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=11A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation

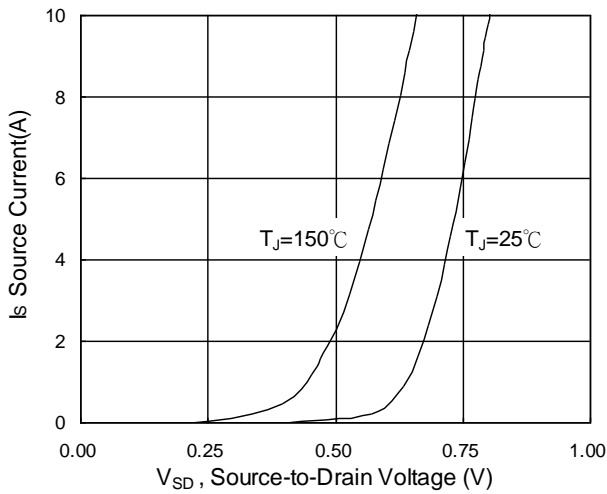
**Typical Characteristics**



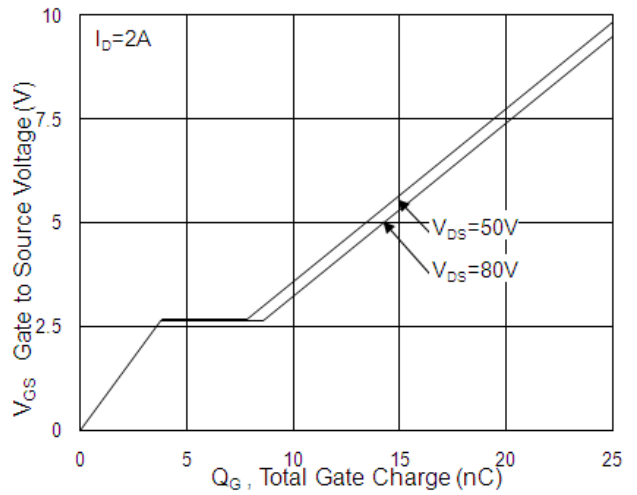
**Fig.1 Typical Output Characteristics**



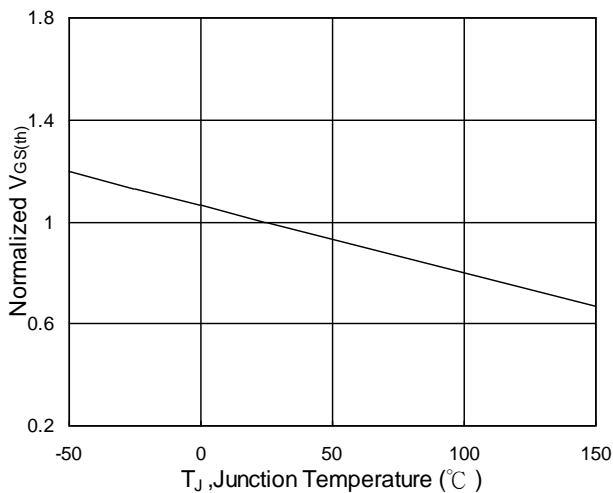
**Fig.2 On-Resistance vs. Gate-Source**



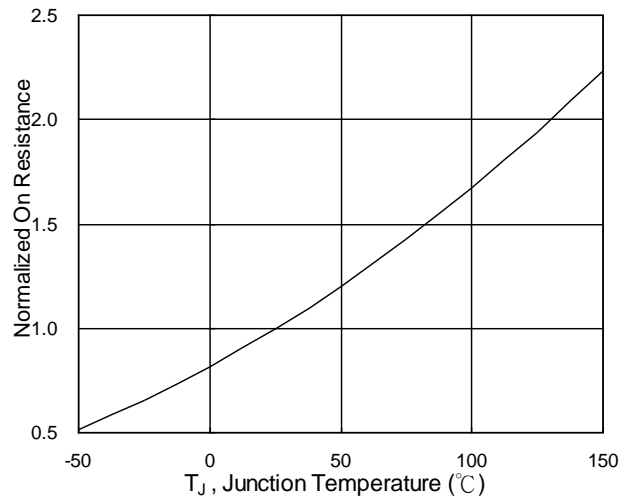
**Fig.3 Forward Characteristics Of Reverse**



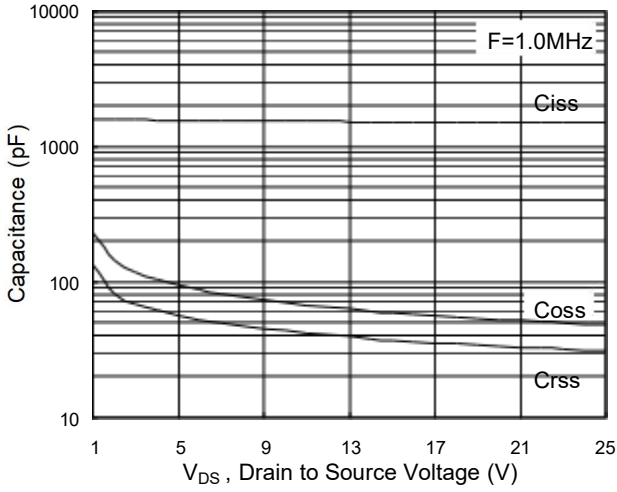
**Fig.4 Gate-Charge Characteristics**



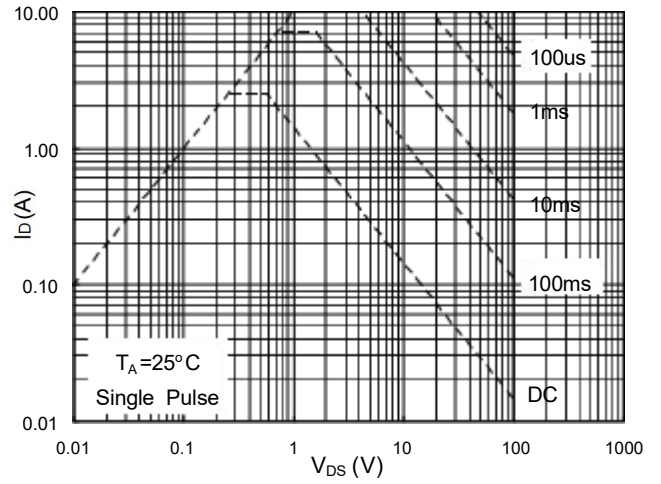
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



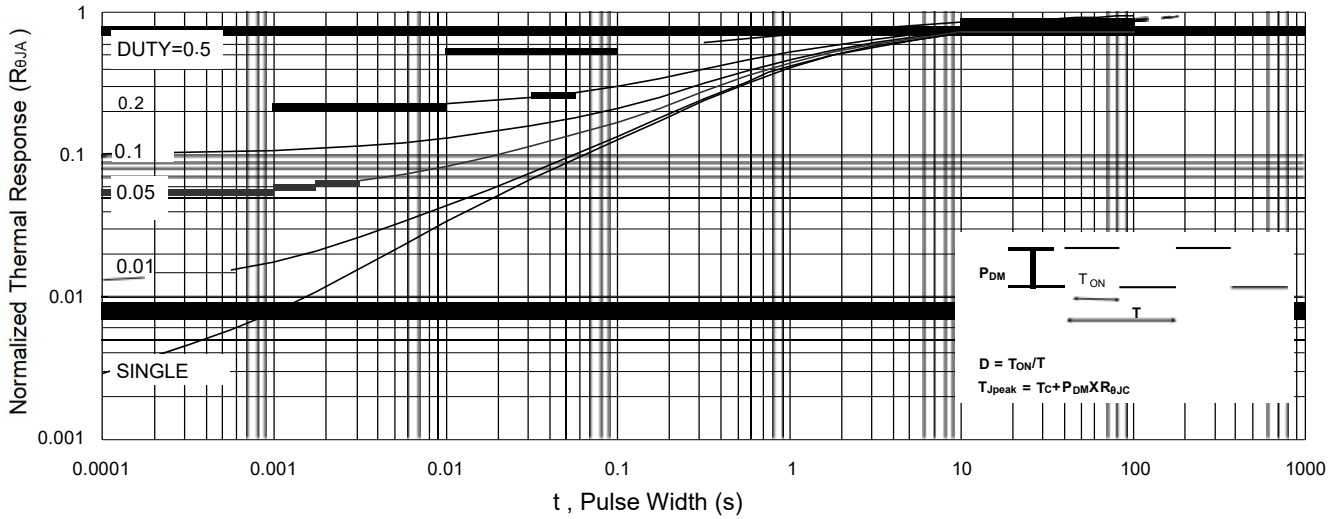
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



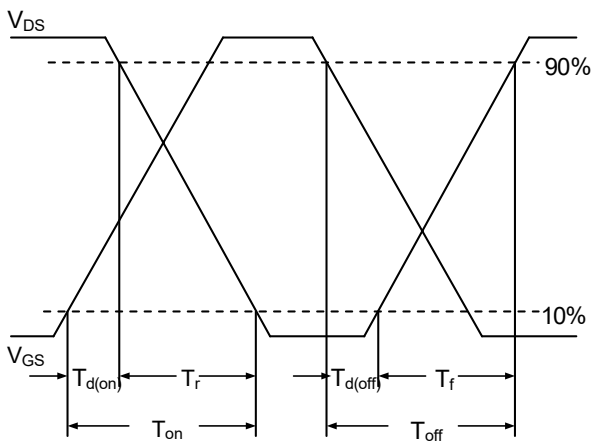
**Fig.7 Capacitance**



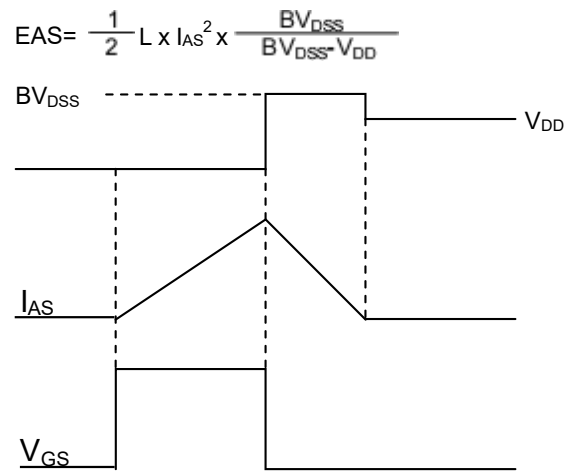
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

**Package Mechanical Data-SOP-8**

